Package Outline Drawing

W4x5.20M

20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)

Rev 0, 01/15

NOTES:


⚠️ Dimension is measured at the maximum bump diameter parallel to primary datum.

⚠️ Primary datum and seating plane are defined by the spherical crowns of the bump.

⚠️ Bump position designation per JESD 95-1, SPP-010.

5. All dimensions are in millimeters.

⚠️ NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.